

500 mA Positive Voltage Regulators

MC78M00, MC78M00A, NCV78M00 Series

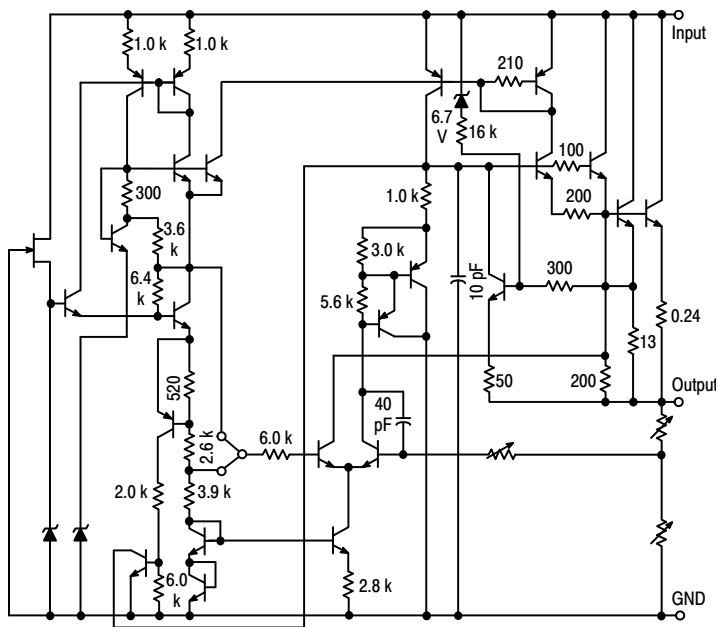
Description

The MC78M00/MC78M00A Series positive voltage regulators are identical to the popular MC7800 Series devices, except that they are specified for only half the output current. Like the MC7800 devices, the MC78M00 three-terminal regulators are intended for local, on-card voltage regulation.

Internal current limiting, thermal shutdown circuitry and safe-area compensation for the internal pass transistor combine to make these devices remarkably rugged under most operating conditions. Maximum output current, with adequate heatsinking is 500 mA.

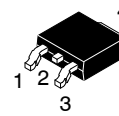
Features

- No External Components Required
- Internal Thermal Overload Protection
- Internal Short Circuit Current Limiting
- Output Transistor Safe-Area Compensation
- MC78M00A High Accuracy ($\pm 2\%$)
Available for 5.0 V, 8.0 V, 12 V and 15 V
- NCV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q100 Qualified and PPAP Capable
- These are Pb-Free Devices

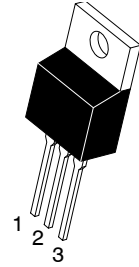


This device contains 28 active transistors.

Figure 1. Representative Schematic Diagram

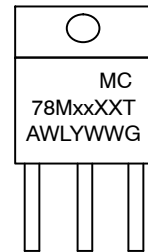


**DPAK-3
DT SUFFIX
CASE 369C**



**TO-220
T SUFFIX
CASE 221AB**

MARKING DIAGRAMS



Heatsink surface
connected to Pin 2.

xx = Voltage Option
XX = Appropriate Suffix Options
A = Assembly Location
WL = Wafer Lot
Y = Year
WW = Work Week
G = Pb-Free Package

Heatsink surface (shown as terminal 4 in case outline drawing) is connected to Pin 2.

xxxxx = Device Type and Voltage Option Code
A = Assembly Location
L = Wafer Lot
Y = Year
WW = Work Week
G = Pb-Free Package

Pin 1. Input
2. Ground
3. Output

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 10-14 of this data sheet.

DEVICE MARKING INFORMATION

See general marking information in the device marking section on page 10 of this data sheet.

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MAXIMUM RATINGS ($T_A = 25^\circ\text{C}$, unless otherwise noted) (Note 1)

Rating	Symbol	Value	Unit
Input Voltage (5.0 V–18 V) (20 V–24V)	V_I	35 40	Vdc
Power Dissipation (Package Limitation) Plastic Package, T Suffix $T_A = 25^\circ\text{C}$ Thermal Resistance, Junction-to-Air Thermal Resistance, Junction-to-Case Plastic Package, DT Suffix $T_A = 25^\circ\text{C}$ Thermal Resistance, Junction-to-Air Thermal Resistance, Junction-to-Case	P_D Q_{JA} Q_{JC} P_D Q_{JA} Q_{JC}	Internally Limited 70 5.0 Internally Limited 92 5.0	$^\circ\text{C/W}$
Operating Junction Temperature Range	T_J	+150	$^\circ\text{C}$
Storage Temperature Range	T_{stg}	–65 to +150	$^\circ\text{C}$

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

- This device series contains ESD protection and exceeds the following tests:
Human Body Model 2000 V per MIL–STD–883, Method 3015.
Machine Model Method 200 V.

MC78M00, MC78M00A, NCV78M00 Series

MC78M12C/AC/B/AB, NCV78M12B ELECTRICAL CHARACTERISTICS

($V_I = 19\text{ V}$, $I_O = 350\text{ mA}$, $T_J = T_{\text{low}}$ to T_{high} , $P_D \leq 5\text{ W}$, unless otherwise noted) (Note 4)

Characteristics	Symbol	Min	Typ	Max	Unit
Output Voltage ($T_J = 25^\circ\text{C}$) MC78M12B/MC78M12C/NCV78M12B MC78M12AB/MC78M12AC	V_O	11.50 11.76	12 12	12.50 12.24	Vdc
Output Voltage Variation ($14.5\text{ Vdc} \leq V_I \leq 27\text{ Vdc}$, $5.0\text{ mA} \leq I_O \leq 350\text{ mA}$) MC78M12B/MC78M12C/NCV78M12B MC78M12AB/MC78M12AC	V_O	11.4 11.5	– –	12.6 12.5	Vdc
Line Regulation ($T_J = 25^\circ\text{C}$, $14.5\text{ Vdc} \leq V_I \leq 30\text{ Vdc}$, $I_O = 200\text{ mA}$)	Reg_{line}	–	8.0	50	mV
Load Regulation ($T_J = 25^\circ\text{C}$, $5.0\text{ mA} \leq I_O \leq 500\text{ mA}$) ($T_J = 25^\circ\text{C}$, $5.0\text{ mA} \leq I_O \leq 200\text{ mA}$)	Reg_{load}	– –	25 10	240 120	mV
Input Bias Current ($T_J = 25^\circ\text{C}$)	I_{IB}	–	3.2	6.0	mA
Quiescent Current Change ($14.5\text{ Vdc} \leq V_I \leq 30\text{ Vdc}$, $I_O = 200\text{ mA}$) ($5.0\text{ mA} \leq I_O \leq 350\text{ mA}$)	ΔI_{IB}	– –	– –	0.8 0.5	mA
Output Noise Voltage ($T_A = 25^\circ\text{C}$, $10\text{ Hz} \leq f \leq 100\text{ kHz}$)	V_n	–	75	–	mV
Ripple Rejection ($I_O = 100\text{ mA}$, $f = 120\text{ Hz}$, $15\text{ V} \leq V_I \leq 25\text{ V}$) ($I_O = 300\text{ mA}$, $f = 120\text{ Hz}$, $15\text{ V} \leq V_I \leq 25\text{ V}$, $T_J = 25^\circ\text{C}$)	RR	55 55	– 80	– –	dB
Dropout Voltage ($T_J = 25^\circ\text{C}$)	$V_I - V_O$	–	2.0	–	Vdc
Short Circuit Current Limit ($T_J = 25^\circ\text{C}$, $V_I = 35\text{ V}$)	I_{OS}	–	350	–	mA
Average Temperature Coefficient of Output Voltage ($I_O = 5.0\text{ mA}$)	DV_O/DT	–	± 0.3	–	mV/ $^\circ\text{C}$
Peak Output Current ($T_J = 25^\circ\text{C}$)	I_O	–	700	–	mA

4. $T_{\text{low}} = 0^\circ\text{C}$ for MC78MxxAC, C
 $= -40^\circ\text{C}$ for MC78MxxAB, B, NCV78MxxAB, B
 $T_{\text{high}} = +125^\circ\text{C}$ for MC78MxxAB, AC, B, C, NCV78MxxAB, B

DEFINITIONS

Line Regulation – The change in output voltage for a change in the input voltage. The measurement is made under conditions of low dissipation or by using pulse techniques such that the average chip temperature is not significantly affected.

Load Regulation – The change in output voltage for a change in load current at constant chip temperature.

Maximum Power Dissipation – The maximum total device dissipation for which the regulator will operate within specifications.

Input Bias Current – That part of the input current that is not delivered to the load.

Output Noise Voltage – The rms AC voltage at the output, with constant load and no input ripple, measured over a specified frequency range.

Long Term Stability – Output voltage stability under accelerated life test conditions with the maximum rated voltage listed in the devices' electrical characteristics and maximum power dissipation.

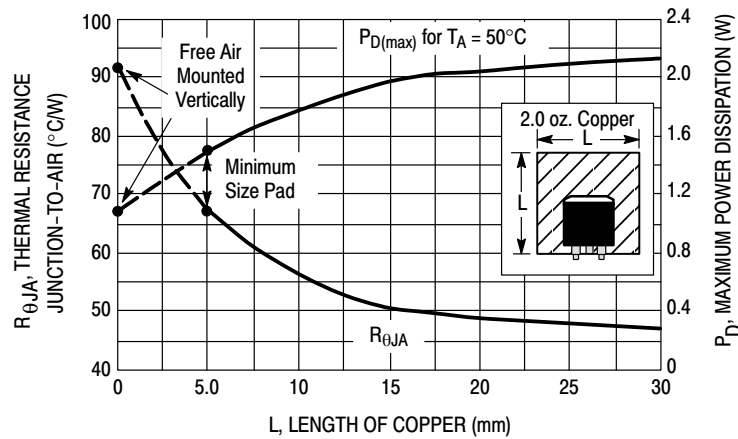


Figure 2. DPAK Thermal Resistance and Maximum Power Dissipation versus P.C.B. Copper Length

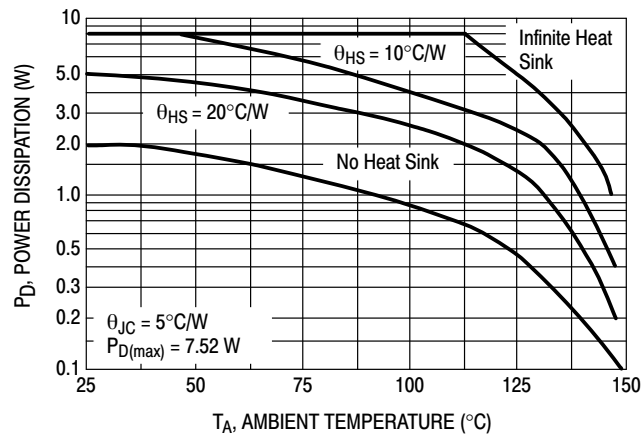


Figure 3. Worst Case Power Dissipation versus Ambient Temperature (TO-220)

MC78M00, MC78M00A, NCV78M00 Series

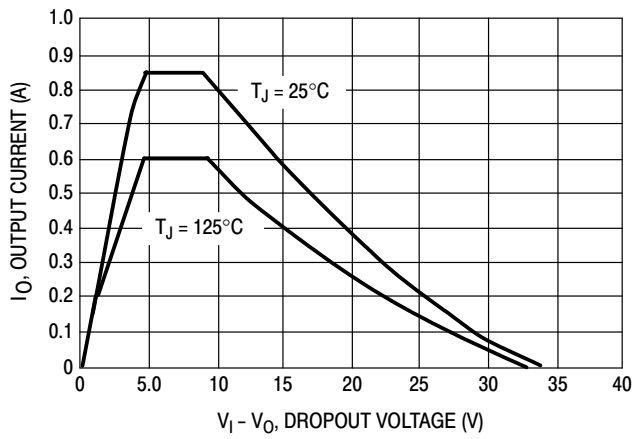


Figure 4. Peak Output Current versus Dropout Voltage

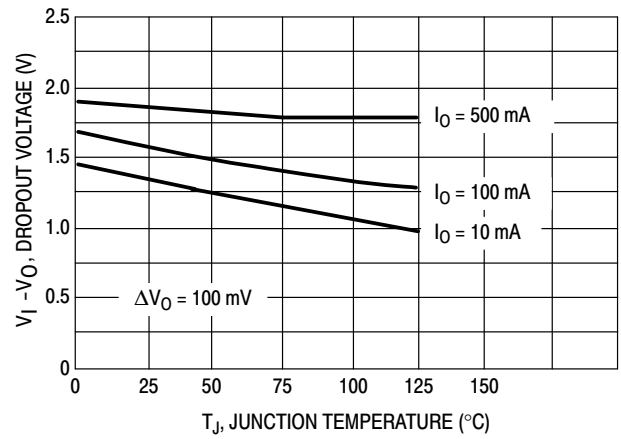


Figure 5. Dropout Voltage versus Junction Temperature

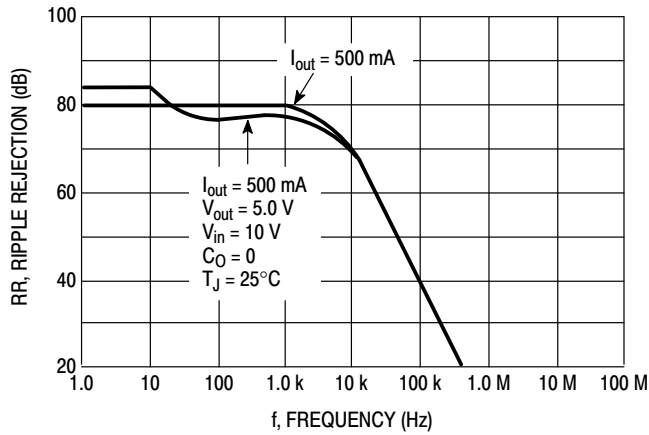


Figure 6. Ripple Rejection versus Frequency

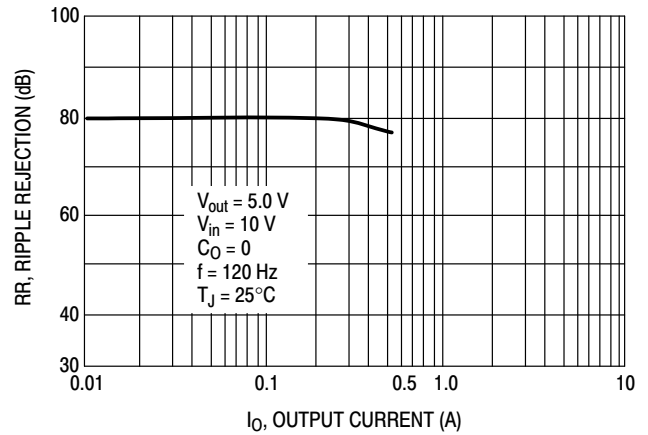


Figure 7. Ripple Rejection versus Output Current

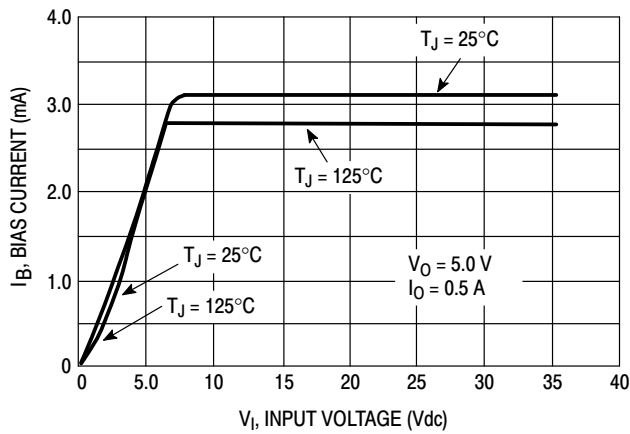


Figure 8. Bias Current versus Input Voltage

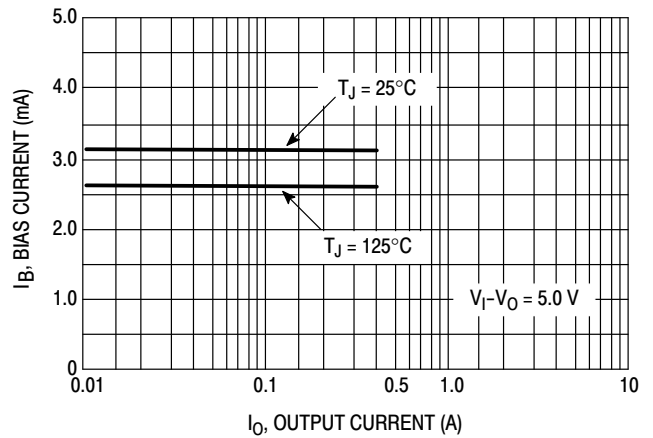


Figure 9. Bias Current versus Output Current

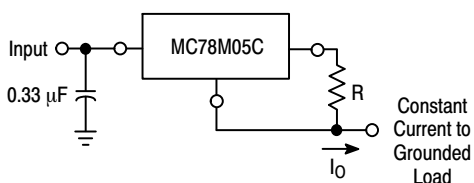
APPLICATIONS INFORMATION

Design Considerations

The MC78M00/MC78M00A Series of fixed voltage regulators are designed with Thermal Overload Protection that shuts down the circuit when subjected to an excessive power overload condition, Internal Short Circuit Protection that limits the maximum current the circuit will pass, and Output Transistor Safe-Area Compensation that reduces the output short circuit current as the voltage across the pass transistor is increased.

In many low current applications, compensation capacitors are not required. However, it is recommended that the regulator input be bypassed with a capacitor if the

regulator is connected to the power supply filter with long wire lengths, or if the output load capacitance is large. An input bypass capacitor should be selected to provide good high frequency characteristics to insure stable operation under all load conditions. A 0.33 μF or larger tantalum, mylar, or other capacitor having low internal impedance at high frequencies should be chosen. The bypass capacitor should be mounted with the shortest possible leads directly across the regulator's input terminals. Normally good construction techniques should be used to minimize ground loops and lead resistance drops since the regulator has no external sense lead.



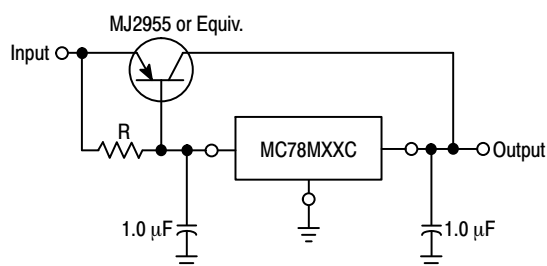
The MC78M00 regulators can also be used as a current source when connected as above. In order to minimize dissipation the MC78M05C is chosen in this application. Resistor R determines the current as follows:

$$I_O = \frac{5.0 \text{ V}}{R} + I_{IB}$$

$I_{IB} = 1.5 \text{ mA}$ over line and load changes.

For example, a 500 mA current source would require R to be a 10 Ω , 10 W resistor and the output voltage compliance would be the input voltage less 7.0 V.

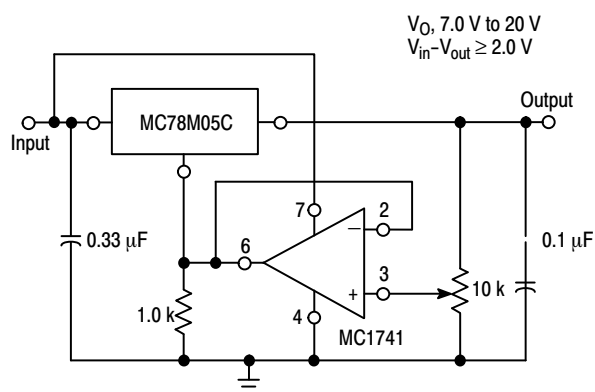
Figure 10. Current Regulator



XX = 2 digits of type number indicating voltage.

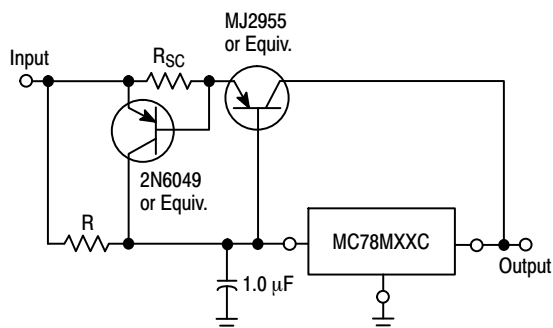
The MC78M00 series can be current boosted with a PNP transistor. The MJ2955 provides current to 5.0 A. Resistor R in conjunction with the V_{BE} of the PNP determines when the pass transistor begins conducting; this circuit is not short circuit proof. Input-output differential voltage minimum is increased by V_{BE} of the pass transistor.

Figure 12. Current Boost Regulator



The addition of an operational amplifier allows adjustment to higher or intermediate values while retaining regulation characteristics. The minimum voltage obtainable with this arrangement is 2.0 V greater than the regulator voltage.

Figure 11. Adjustable Output Regulator

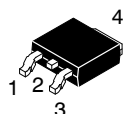


XX = 2 digits of type number indicating voltage.

The circuit of Figure 12 can be modified to provide supply protection against short circuits by adding a short circuit sense resistor, R_{SC} , and an additional PNP transistor. The current sensing PNP must be able to handle the short circuit current of the three-terminal regulator. Therefore, a 4.0 A plastic power transistor is specified.

Figure 13. Current Boost with Short Circuit Protection

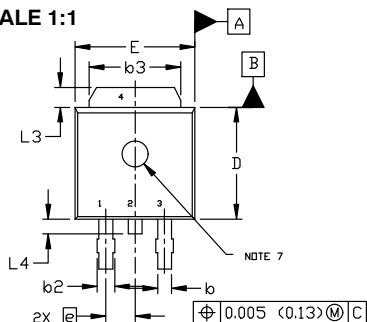
MECHANICAL CASE OUTLINE PACKAGE DIMENSIONS



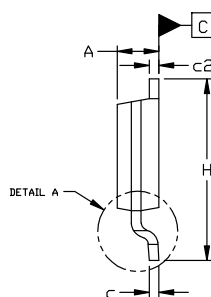
DPAK (SINGLE GAUGE) CASE 369C ISSUE G

DATE 31 MAY 2023

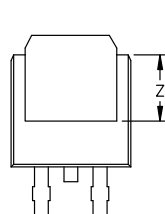
SCALE 1:1



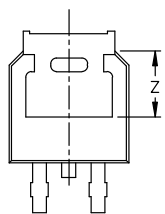
TOP VIEW



SIDE VIEW

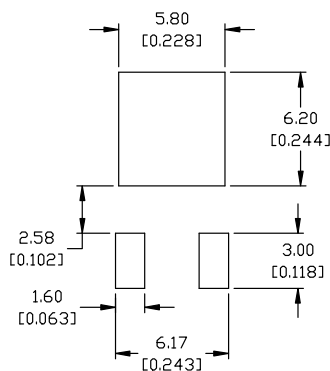


BOTTOM VIEW



BOTTOM VIEW

ALTERNATE
CONSTRUCTIONS



RECOMMENDED MOUNTING FOOTPRINT*

*FOR ADDITIONAL INFORMATION ON OUR Pb-FREE STRATEGY AND SOLDERING DETAILS, PLEASE DOWNLOAD THE ON SEMICONDUCTOR SOLDERING AND MOUNTING TECHNIQUES REFERENCE MANUAL, SOLDERRM/D.

STYLE 1:

PIN 1. BASE
2. COLLECTOR
3. EMITTER
4. COLLECTOR

STYLE 2:

PIN 1. GATE
2. DRAIN
3. SOURCE
4. DRAIN

STYLE 3:

PIN 1. ANODE
2. CATHODE
3. ANODE
4. CATHODE

STYLE 4:

PIN 1. CATHODE
2. ANODE
3. GATE
4. ANODE

STYLE 5:

PIN 1. GATE
2. ANODE
3. CATHODE
4. ANODE

STYLE 6:

PIN 1. MT1
2. MT2
3. GATE
4. MT2

STYLE 7:

PIN 1. GATE
2. COLLECTOR
3. EMITTER
4. COLLECTOR

STYLE 8:

PIN 1. N/C
2. CATHODE
3. ANODE
4. CATHODE

STYLE 9:

PIN 1. ANODE
2. CATHODE
3. RESISTOR ADJUST
4. CATHODE

STYLE 10:

PIN 1. CATHODE
2. ANODE
3. CATHODE
4. ANODE

NOTES:

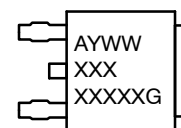
1. DIMENSIONING AND TOLERANCING ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: INCHES
3. THERMAL PAD CONTOUR OPTIONAL WITHIN DIMENSIONS b3, L3, AND Z.
4. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR BURRS. MOLD FLASH, PROTRUSIONS, OR GATE BURRS SHALL NOT EXCEED 0.006 INCHES PER SIDE.
5. DIMENSIONS D AND E ARE DETERMINED AT THE OUTERMOST EXTREMES OF THE PLASTIC BODY.
6. DATUMS A AND B ARE DETERMINED AT DATUM PLANE H.
7. OPTIONAL MOLD FEATURE.

DIM	INCHES		MILLIMETERS	
	MIN.	MAX.	MIN.	MAX.
A	0.086	0.094	2.18	2.38
A1	0.000	0.005	0.00	0.13
b	0.025	0.035	0.63	0.89
b2	0.028	0.045	0.72	1.14
b3	0.180	0.215	4.57	5.46
c	0.018	0.024	0.46	0.61
c2	0.018	0.024	0.46	0.61
D	0.235	0.245	5.97	6.22
E	0.250	0.265	6.35	6.73
e	0.090	BSC	2.29	BSC
H	0.370	0.410	9.40	10.41
L	0.055	0.070	1.40	1.78
L1	0.114	REF	2.90	REF
L2	0.020	BSC	0.51	BSC
L3	0.035	0.050	0.89	1.27
L4	----	0.040	---	1.01
Z	0.155	----	3.93	---

GENERIC MARKING DIAGRAM*



IC



Discrete

XXXXXX = Device Code
A = Assembly Location
L = Wafer Lot
Y = Year
WW = Work Week
G = Pb-Free Package

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "•", may or may not be present. Some products may not follow the Generic Marking.

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